

## 正誤表

9B610T-176SD1NQ ドキュメント 第 1v4 版 (9B610T-176SD1NQ-manual-1v4)  
に対する正誤表です。

32 ビット・マイクロコントローラ  
FM3 ファミリ

2014.5.12

※  : 訂正箇所

日付	ページ	項目	訂正内容
2014/ 5/12	回路図 3/4 ページ (9-A) 3/4 ページ (9-D)	R61 の抵抗値表記 R96 の抵抗値表記	(誤) 18.1K (正) <span style="background-color: #cccccc;">18.2K</span>
	回路図 3/4 ページ (11-B) 3/4 ページ (11-E)	CN14 のコネクタ表記 CN20 のコネクタ表記	(誤) TLA-6T718 (正) <span style="background-color: #cccccc;">TM11RD-5TANA-A-88</span>

1. Power Supply Selection

POWER SOURCE	CN24 SETTING
DC 5V	1-2
USB CH0 Vbus	2-3

2. Switch, Jumper Pin Settings

	FUNCTION	SETTING	ACTION
SW1	MD1	1-2	HIGH
		2-3	LOW
SW2	MD0	1-2	HIGH
		2-3	LOW
SW3	RESET	PUSH ON	RESET
		PUSH OFF	NOT RESET
CN1	ETM PIN#11&13	1-2	OPEN
		2-3	GND
CN2	ETM PIN#9	1-2	OPEN
		2-3	GND
CN3	MD1	1-2	OPEN
		2-3	CONNECT
CN5	JTAG PIN#11	1-2	OPEN
		2-3	CONNECT
CN7	JTAG PIN#17	1-2	OPEN
		2-3	CONNECT
CN9	JTAG PIN#19	1-2	OPEN
		2-3	CONNECT
CN10	JTAG PIN#2	1-2	PULL-UP
		2-3	OPEN
CN11	USB CH0 D- DEVICE/HOST SEL.	1-2	DEVICE
		2-3	HOST
CN12	USB CH0 D+ DEVICE/HOST SEL.	1-2	DEVICE
		2-3	HOST
CN16	USB CH1 Vbus DET. CONNECT/PULL-UP SEL.	1-2	PULL-UP
		2-3	CONNECT

CN17	USB CH1 D- DEVICE/HOST SEL.	1-2	DEVICE
		2-3	HOST
CN18	USB CH1 D+ DEVICE/HOST SEL.	1-2	DEVICE
		2-3	HOST
CN24	POWER SUPPLY SEL. DC5V/USB CH1 Vbus	1-2	DC5V
		2-3	USB CH1 Vbus
CN29	AVRH	1-2	3.3V
		2-3	OPEN
CN30	P22(MCU PIN#125)	1-2	PULL-UP
		2-3	PULL-DOWN

Revision history:

2012/02/03 Initial revision

2012/02/13 Correct typo at “1. Power Supply Selection”, from “USB CH1 Vbus” to “USB CH0 Vbus”

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The following precautions apply to the product described in this manual.

Before moving the product, be sure to turn off all the power supplies and unplug the cables. Watch your step when carrying the product. Do not use the product in an unstable location such as a place exposed to strong vibration or a sloping surface.

Do not place anything on the product or expose the product to physical shocks. Do not carry the product after the power has been turned on. Doing so may cause a malfunction due to overloading or shock.

Since the product contains many electronic components, keep it away from direct sunlight, high temperature, and high humidity to prevent condensation. Do not use or store the product where it is exposed to much dust or a strong magnetic or electric field for an extended period of time.

Inappropriate operating or storage environments may cause a fault.

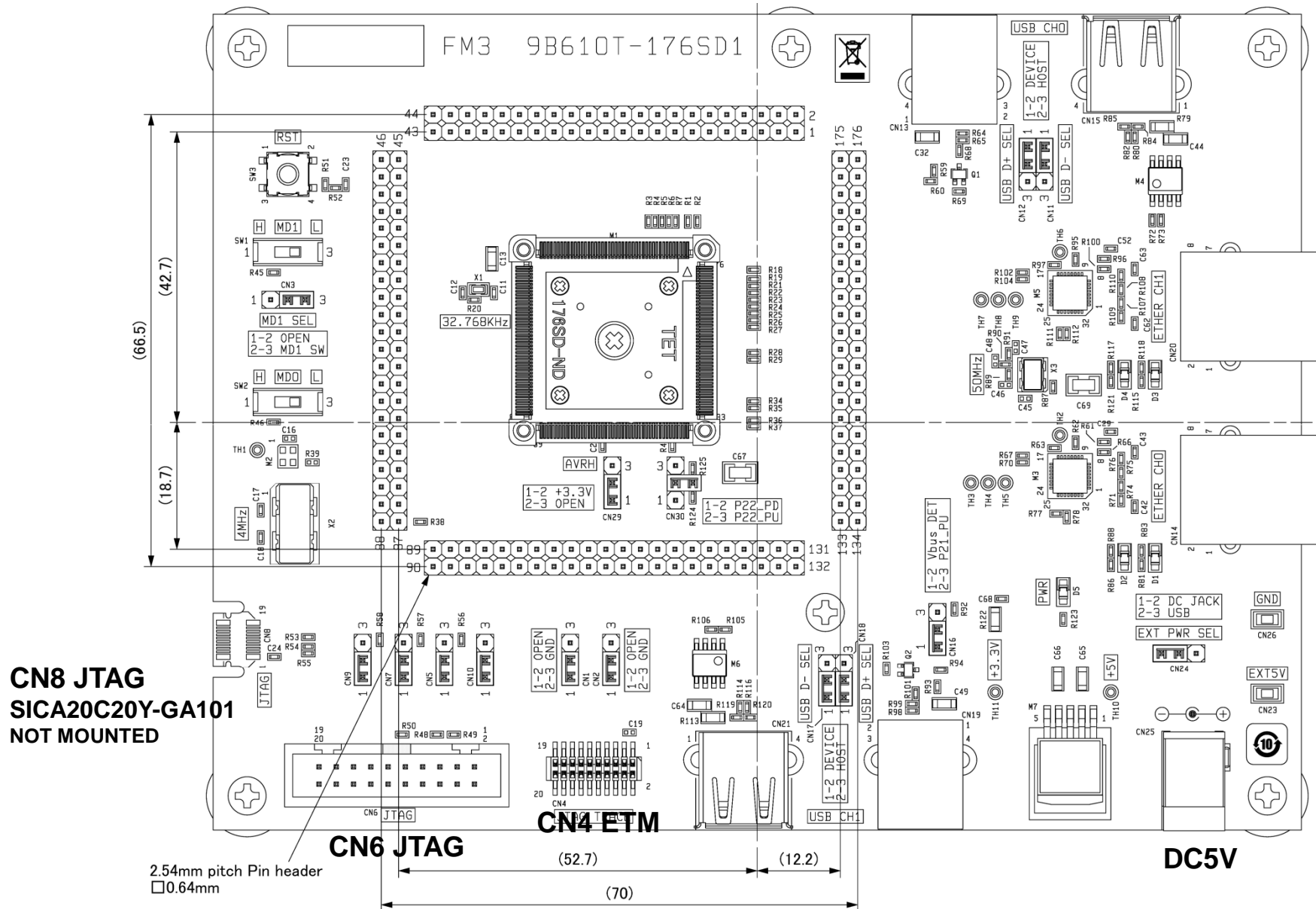
Use the product within the ranges given in the specifications. Operation over the specified ranges may cause a fault.

To prevent electrostatic breakdown, do not let your finger or other object come into contact with the metal parts of any of the connectors. Before handling the product, touch a metal object (such as a door knob) to discharge any static electricity from your body.

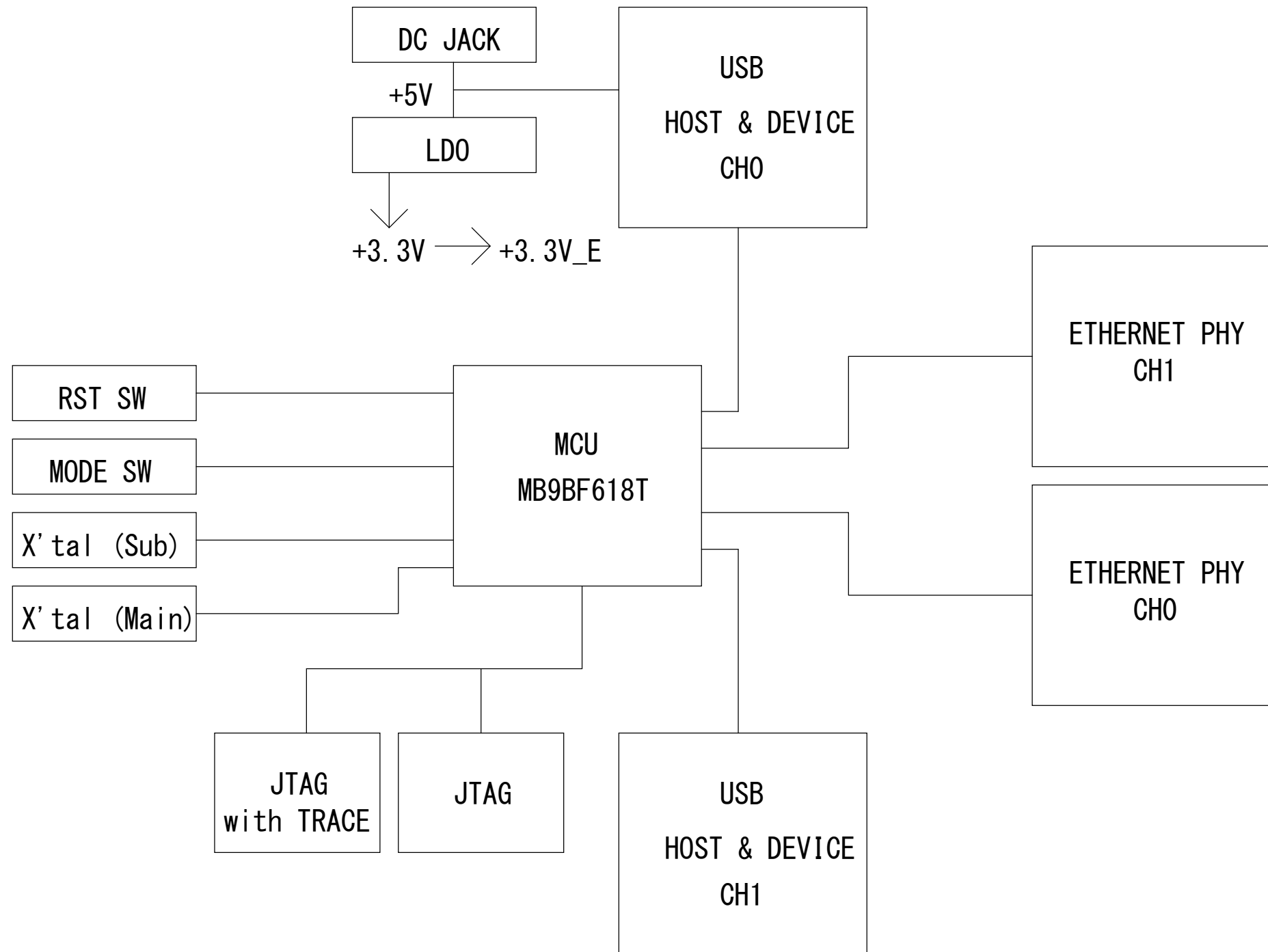
Always turn the power off before connecting or disconnecting any cables from the product. When unplugging a cable, unplug the cable by holding the connector part without pulling on the cable itself. Pulling the cable itself or bending it may expose or disconnect the cable core, resulting in a fault.

It is recommended that it be stored in the original packaging. Transporting the product may cause a damage or fault. Therefore, keep the packaging materials and use them when re-shipping the product.

# 9B610T-176SD1NQ

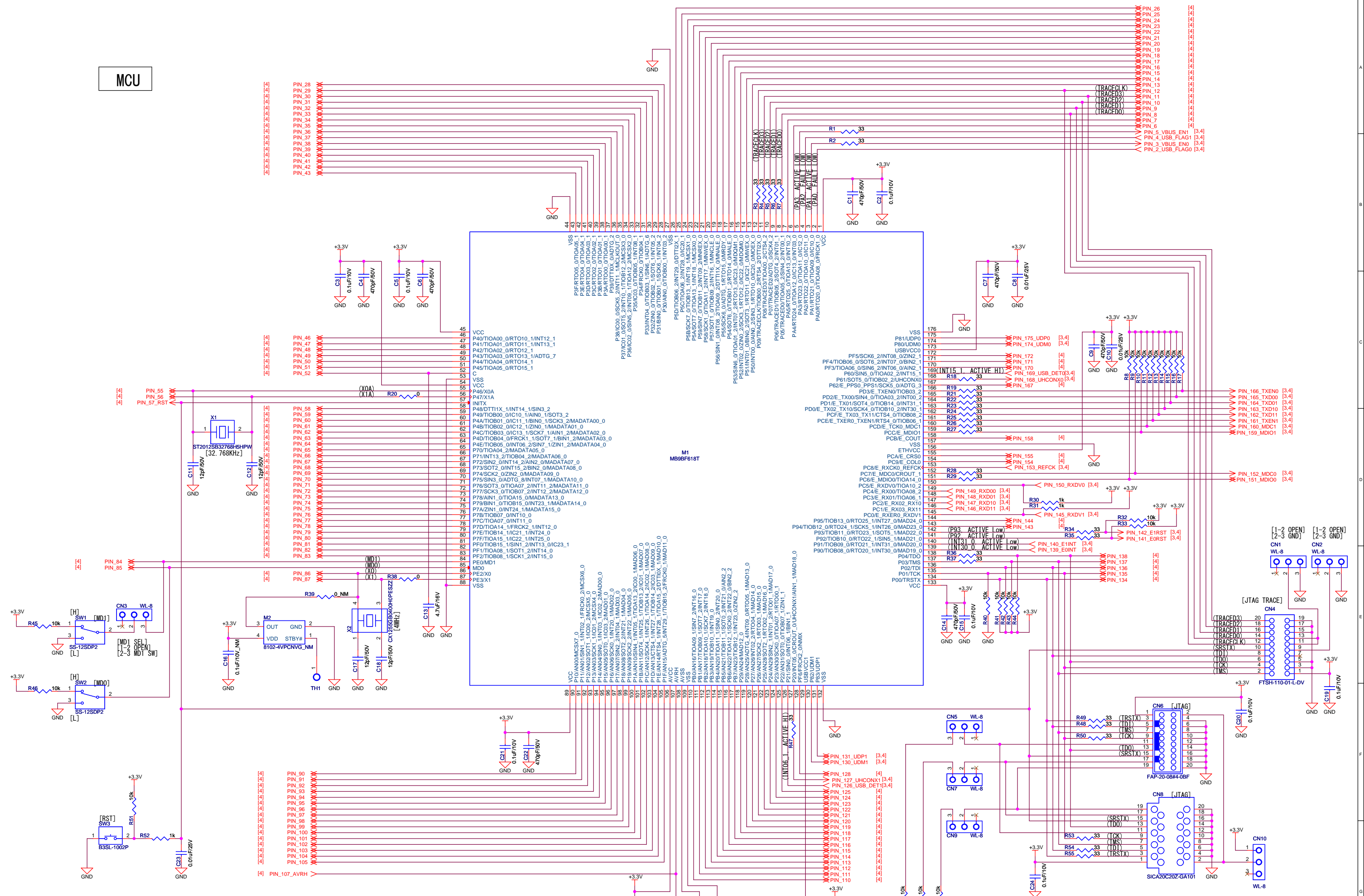


# [BLOCK DIAGRAM]



								Title 9B610T-176SD1	
								<OrgAddr3>	
								Draw.No. <Doc>	
Ed.	Date	Desig.	Check	Appr.	Description				
Desig.	20110929		Check		Appr.				
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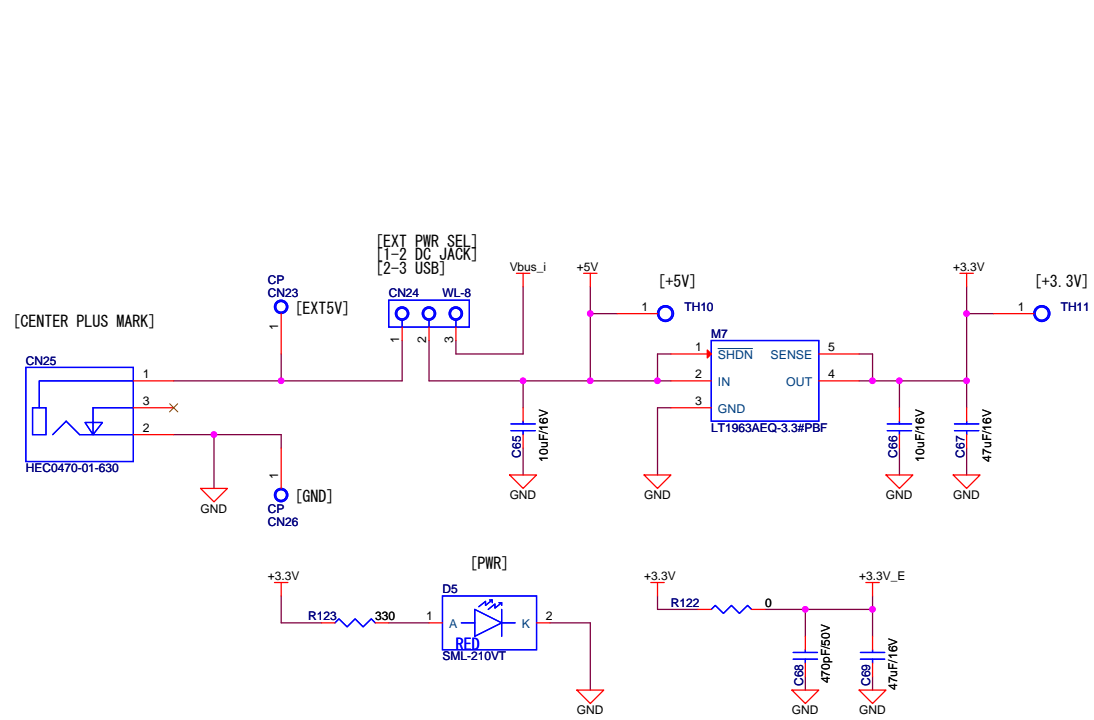
MCU



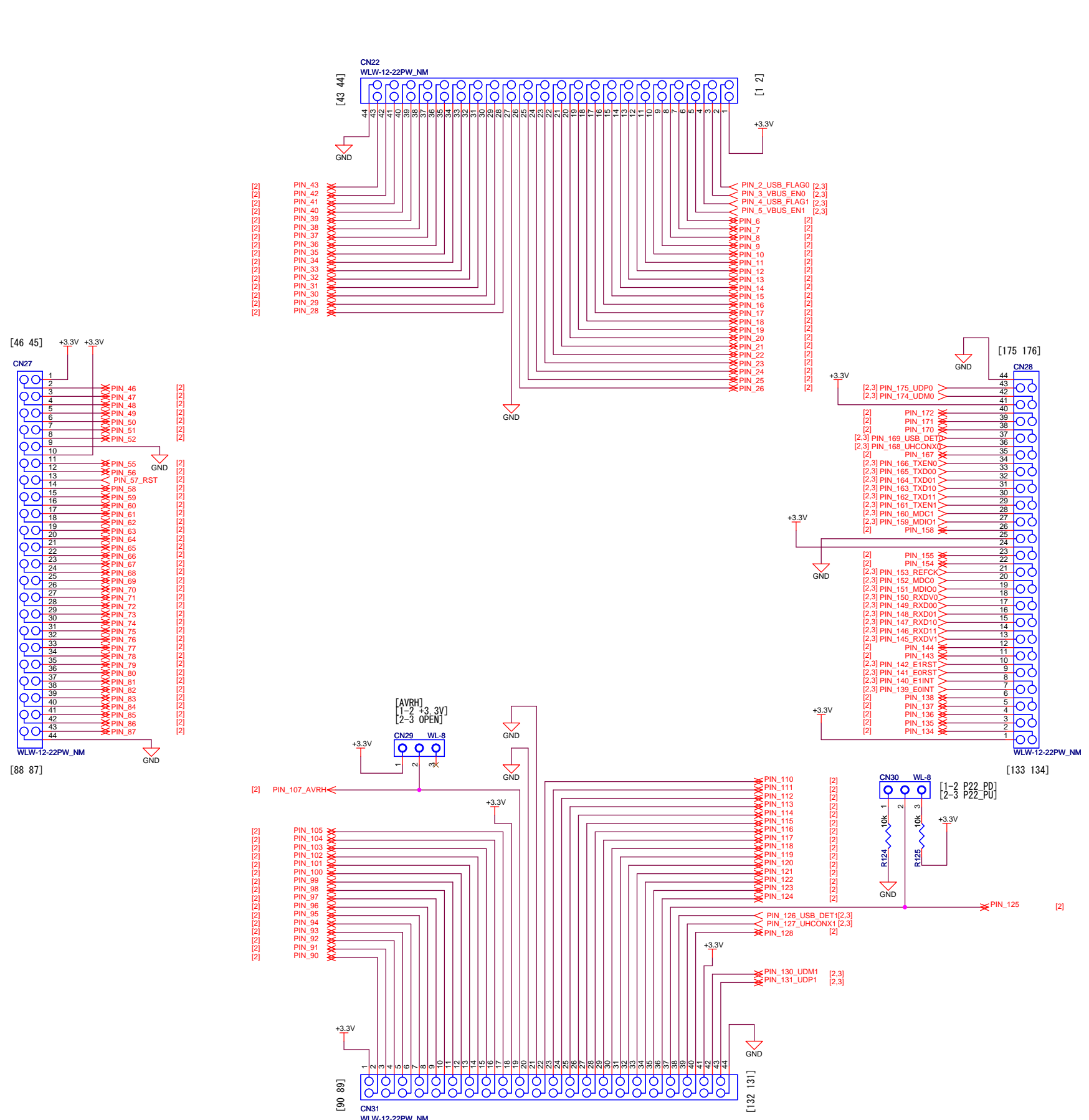




# POWER



# MCU SIGNAL MONITOR



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## 中華人民共和國「電子情報製品污染防止管理弁法」の対応

Compliance with Administration on the Control of Pollution Caused by Electronic Information Products of the People's Republic of China

## 电子信息产品污染控制管理办法（第 39 号）



这标记是按照 2006 年 2 月 28 日公布的[电子信息产品污染控制管理办法]以及 SJ/T11364-2006[电子信息产品污染控制标识要求]在中国销售的电子信息产品的环保使用期限。如遵守关于这产品的安全或使用上的注意，在这期限内（从生产日期起算）不会因产品中的有害物质漏到外部，或发生突然变异，而引起环境污染和对人体或财产的重大影响。

## 产品中有毒有害物质或元素的名称及含量

部件名称	有毒有害物质或元素					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr(VI))	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
印刷线路板	○	○	○	○	○	○

○：表示该有毒有害物质在该部件所有均质材料中的含量均在 SJ/T11363-2006 规定的限量要求以下。  
 ×：表示该有毒有害物质至少在该部件的某一均质材料中的含量超出 SJ/T11363-2006 规定的限量要求。